

COMSOL Conference – Lausanne – October 2018

Nanoscale Heat Transport and Phonon Hydrodynamics

A. Beardo, L. Sendra, J. Bafaluy, J. Camacho, F. X. Alvarez

Universitat Autònoma de Barcelona
Physics Department
albert.beardo@uab.cat



Group and Collaborators



PHYSICS DEPT.

F. Xavier Alvarez
Albert Beardo
Javier Bafaluy
David Jou
Juan Camacho
Lluc Sendra

ELCTR. ENG. DEPT.

Xavier Cartoixà

MATH DEPT.

Marc Calvo
Tim Mayers
Mark Hernessy

PURUE UNIVERSITY

Ali Shakouri
Amirkoushar Ziabari

ICMAB

Riccardo Rurali
Pol Torres

UNIVIVERSITY OF CAGLIARY

Claudio Melis

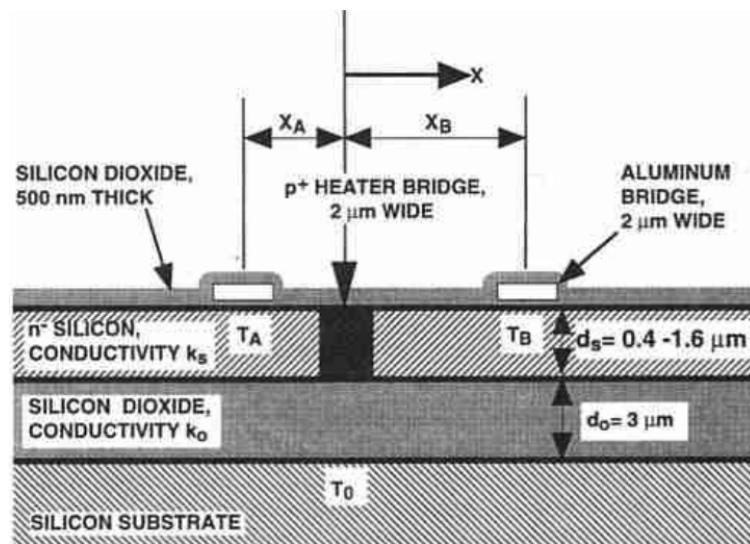
- Motivation
- Nanoscale Heat Transport
- Kinetic Collective Model
- Experimental validation
- Conclusions

2>> Motivation

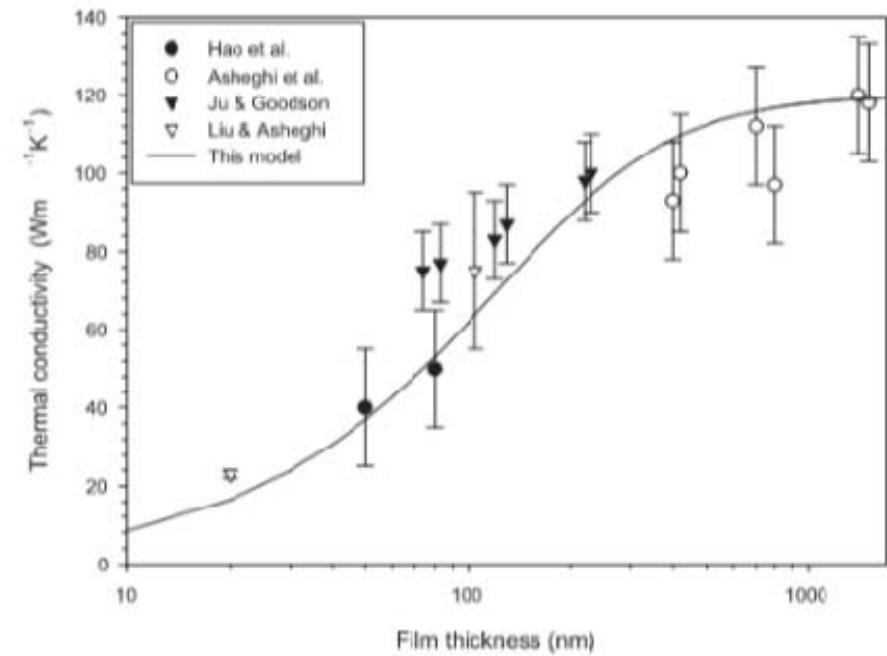
Fourier / Diffusive model

$$c \frac{dT}{dt} = -\nabla \cdot q$$

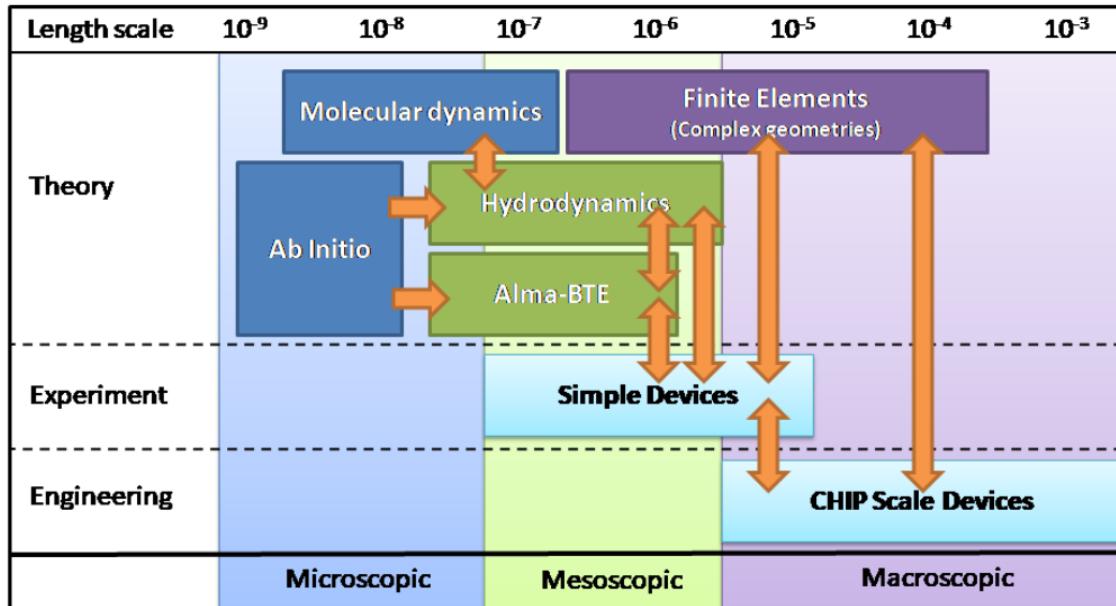
$$q = -\kappa \nabla T$$



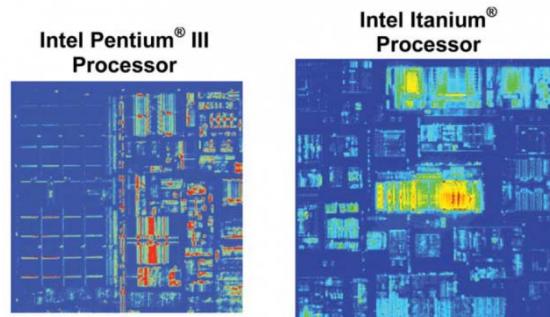
Breakdown of Fourier law
at reduced length and time
scales.



3>> Motivation



- * Obtain an improved equation of transport derived from the **microscopic description of the phonons dynamics**.
- * Improve the thermal management in nano scale semiconductor devices.



Predict the appearance of hot spots.

4>> Nanoscale Heat Transport

Boltzmann Transport Equation

Describes the non equilibrium evolution of the **phonons** (energy carriers).



BTE output

Phonon distribution function $f(\kappa, x, t)$



Moment description

$$M_i(x, t) = \int \kappa \cdots \kappa f(\kappa, x, t)$$



Grad/Chapman-Enskog equations

Guyer-Krumhansl equations



Thermodynamic output

Heat Flux \mathbf{q}

Temperature T

Hydrodynamic Equations

$$c \frac{dT}{dt} + \nabla \cdot \mathbf{q} = 0$$

$$\tau \frac{\partial \mathbf{q}}{\partial t} + \mathbf{q} + \kappa \nabla T = \ell^2 (\nabla^2 \mathbf{q} + 2 \nabla \nabla \cdot \mathbf{q})$$

Relaxation Time Bulk Thermal conductivity Non Local Length

Slip Boundary Conditions

$$\mathbf{q}_t = -C\ell \nabla \mathbf{q}_t \cdot \mathbf{n}$$

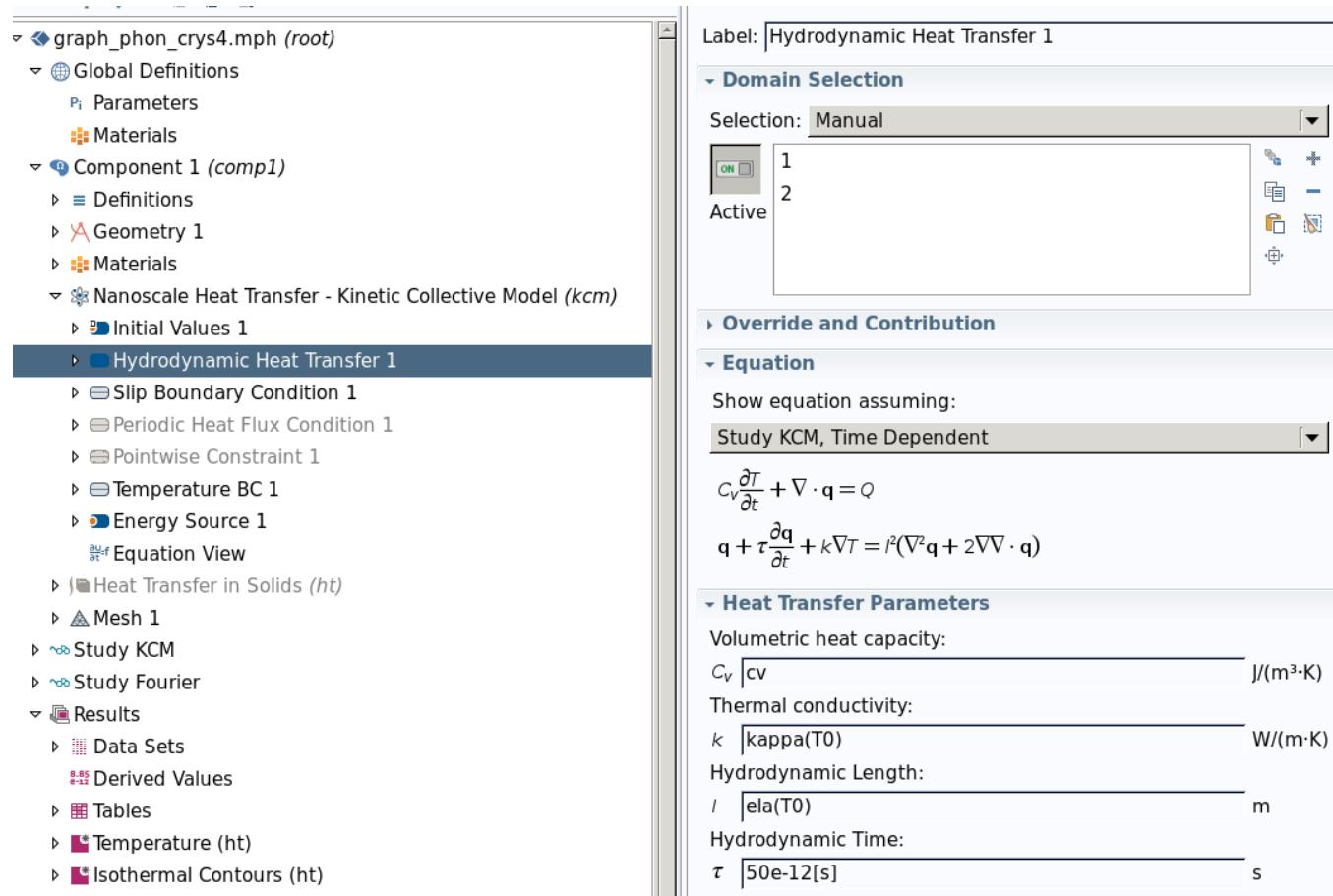
$$\mathbf{q} \cdot \mathbf{n} = 0$$

Surface
specularity

- Calculated from first principles.
- Material properties.
- Only depend on temperature.

6>> Kinetic Collective Model

COMSOL interface for solving thermal transport in **complex geometries**.



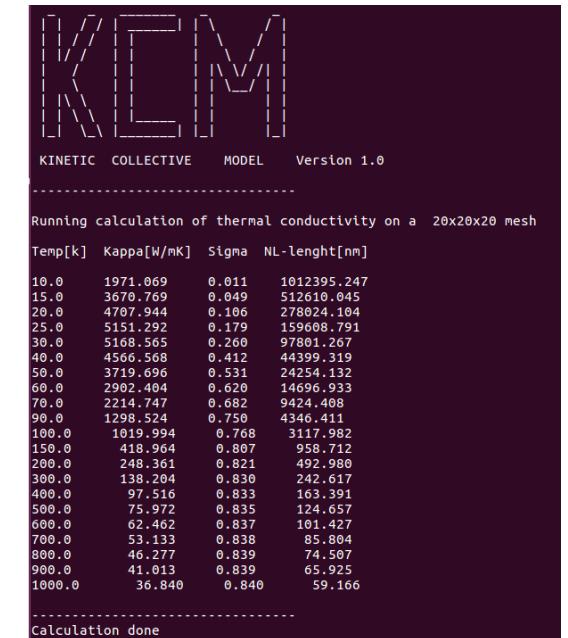
The screenshot shows the COMSOL interface with the following details:

- Project Tree:** graph_phon_crys4.mph (root) -> Global Definitions (Parameters, Materials) -> Component 1 (comp1) (Definitions, Geometry 1, Materials) -> Nanoscale Heat Transfer - Kinetic Collective Model (kcm) (Initial Values 1, Hydrodynamic Heat Transfer 1, Slip Boundary Condition 1, Periodic Heat Flux Condition 1, Pointwise Constraint 1, Temperature BC 1, Energy Source 1, Equation View, Heat Transfer in Solids (ht), Mesh 1, Study KCM, Study Fourier) -> Results (Data Sets, Derived Values, Tables, Temperature (ht), Isothermal Contours (ht)).
- Study Settings:**
 - Label:** Hydrodynamic Heat Transfer 1
 - Domain Selection:** Selection: Manual, Active: 1, 2.
 - Equation:** Show equation assuming: Study KCM, Time Dependent.

$$C_v \frac{\partial T}{\partial t} + \nabla \cdot q = Q$$

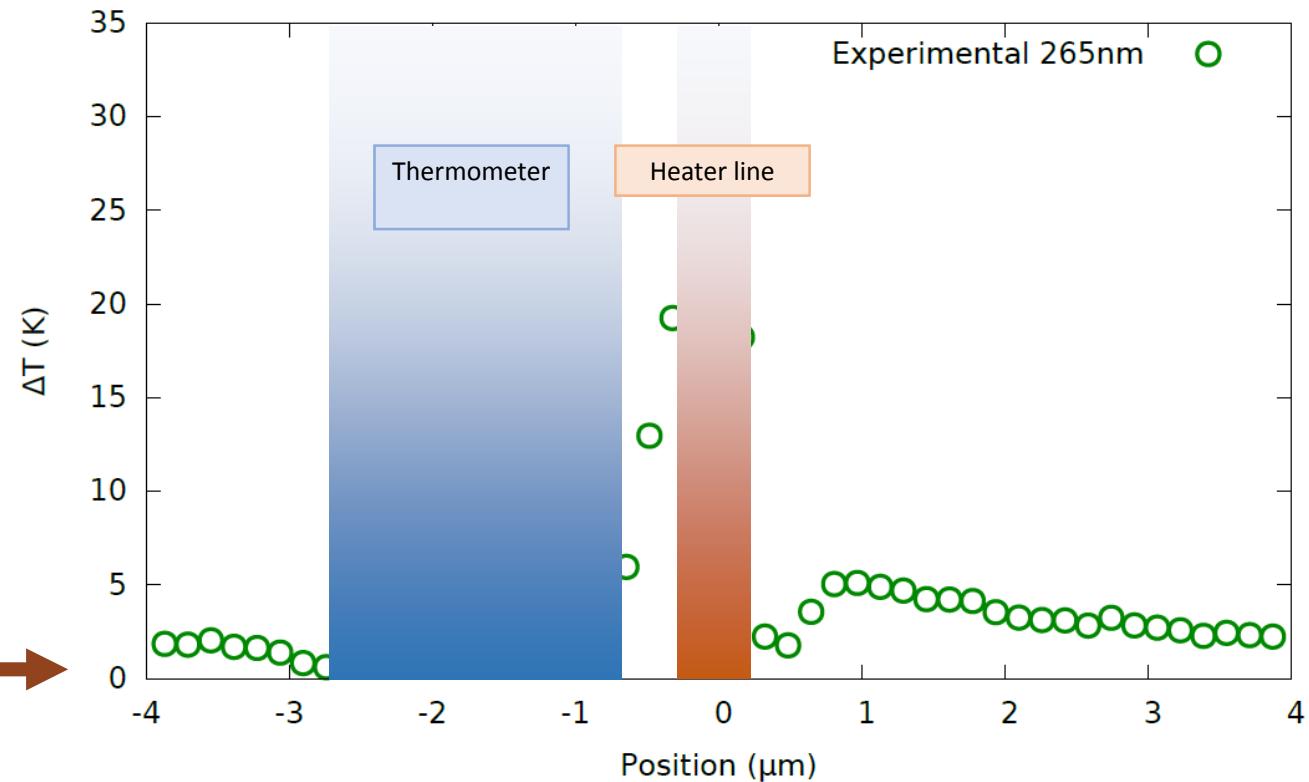
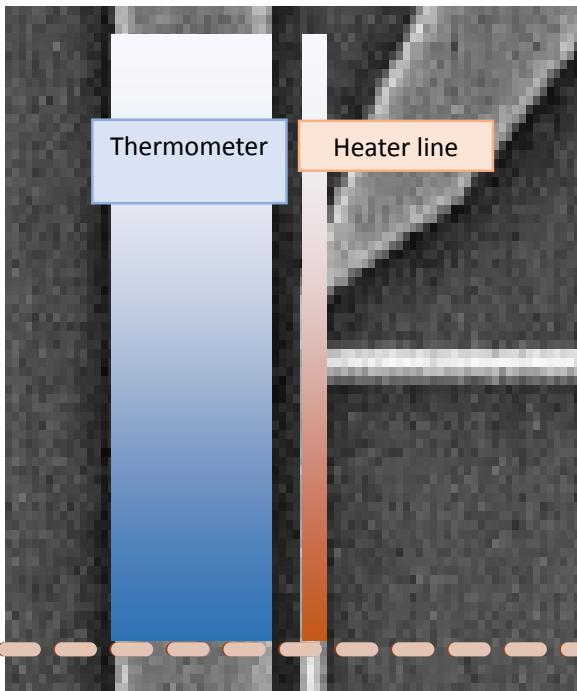
$$q + \tau \frac{\partial q}{\partial t} + k \nabla T = l^2 (\nabla^2 q + 2 \nabla \nabla \cdot q)$$
 - Heat Transfer Parameters:**
 - Volumetric heat capacity: C_v [cv] $J/(m^3 \cdot K)$
 - Thermal conductivity: k [kappa(T0)] $W/(m \cdot K)$
 - Hydrodynamic Length: l [ela(T0)] m
 - Hydrodynamic Time: τ [50e-12[s]] s

First principles calculation of κ, l, τ



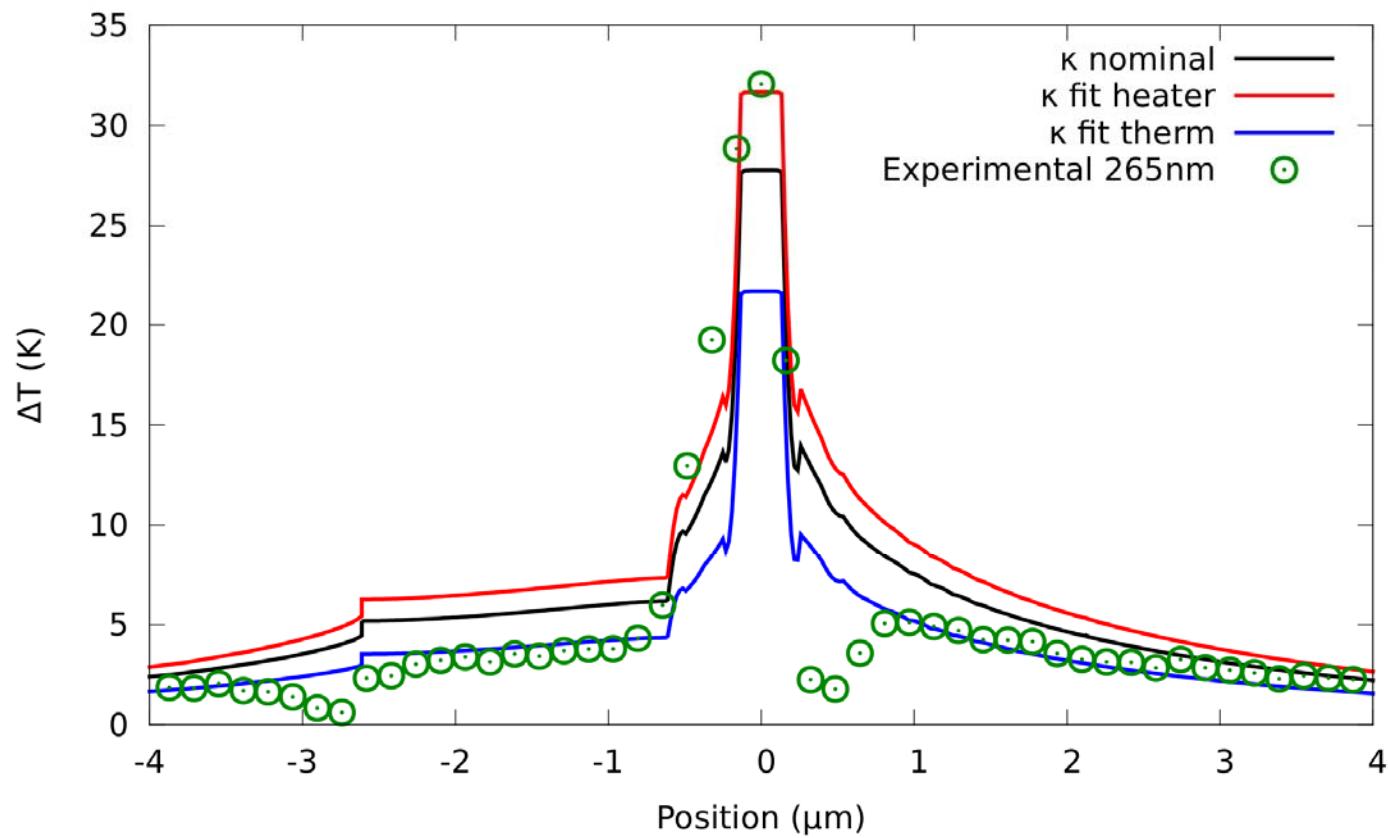
- Discontinuous Galerkin implementation of the boundary conditions.
- Stabilization.
- Multiphysics coupling with Fourier domains (metal domains).

Heater on InGaAs substrate.



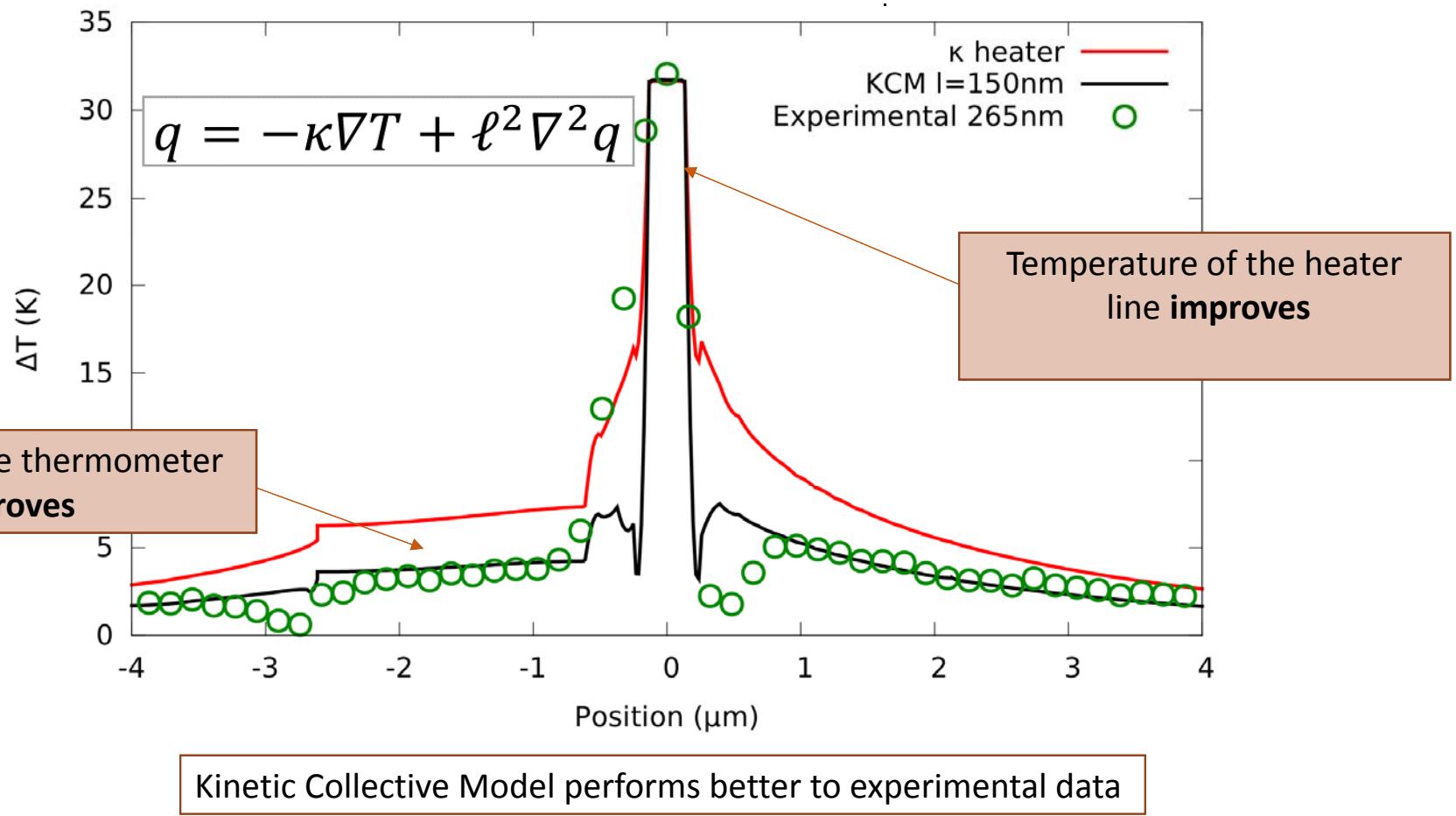
We obtain a thermal map of the surface of the sample using the optical setup.
Heater line and thermometer are also obtained using electrical measurements.

8>> Experimental validation



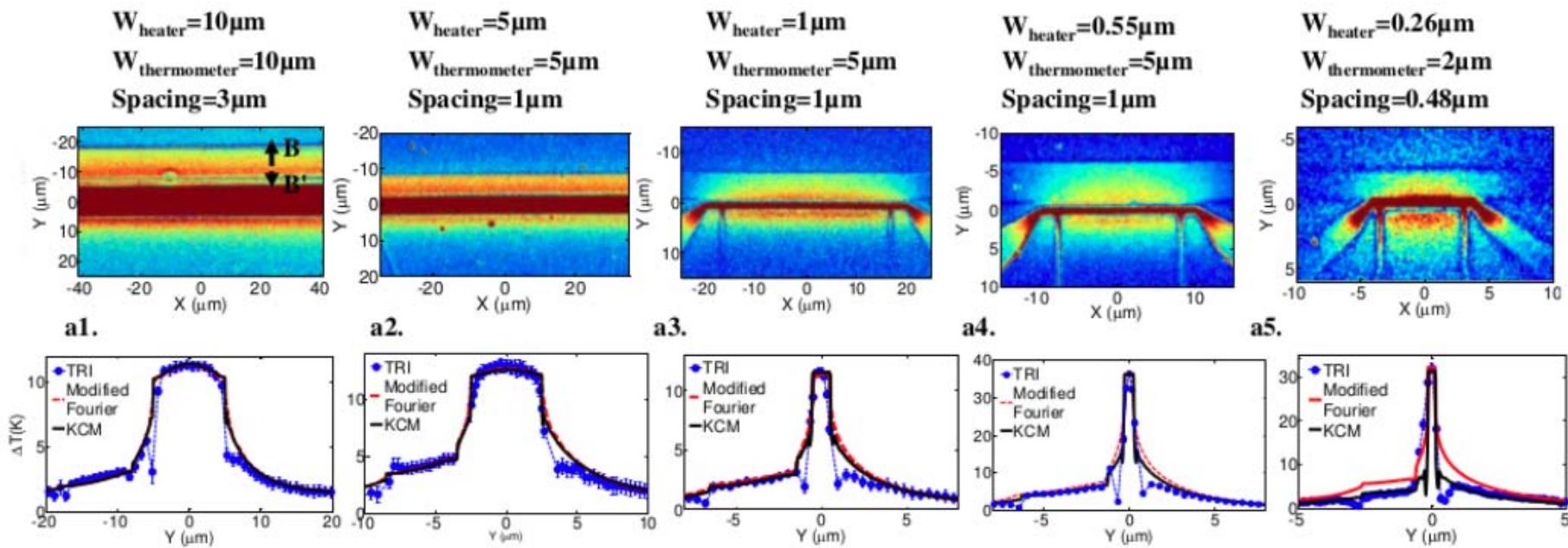
Fourier's law cannot describe thermal transport in this setup. New equation is needed.

9>> Experimental validation



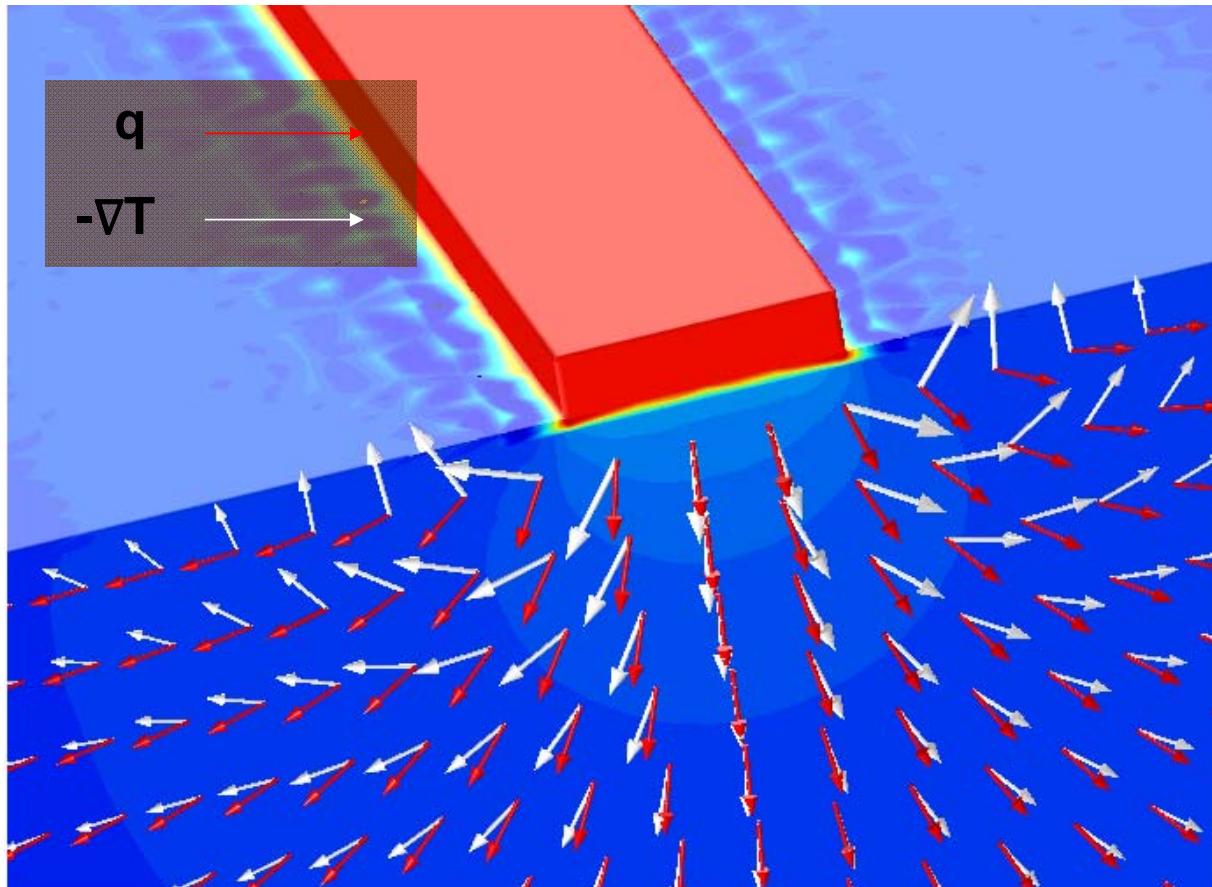
10>> Experimental validation

- At large sizes we recover Fourier model.
- The smaller the size, the larger the effect.
- At extremely small sizes, the model fails due ballistic effects.



11>> Experimental validation

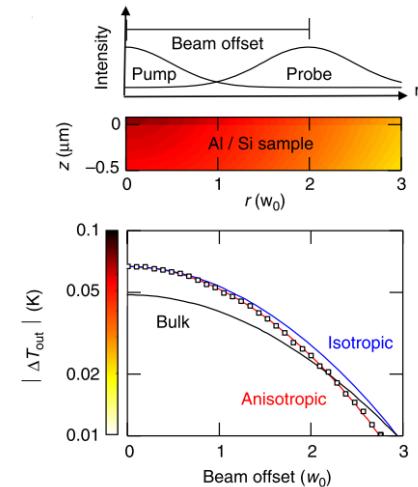
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ANISOTROPIC BEHAVIOUR

Temperature gradient and heat flux are not parallel because of the contribution of the new hydrodynamic term. This is interpretable as a **vorticity** appearing.

Wilson and Cahill. Nat Commun 5, 5075 (2014)



Torres et al. Phys. Rev. Mat., 2, 076001 (2018)

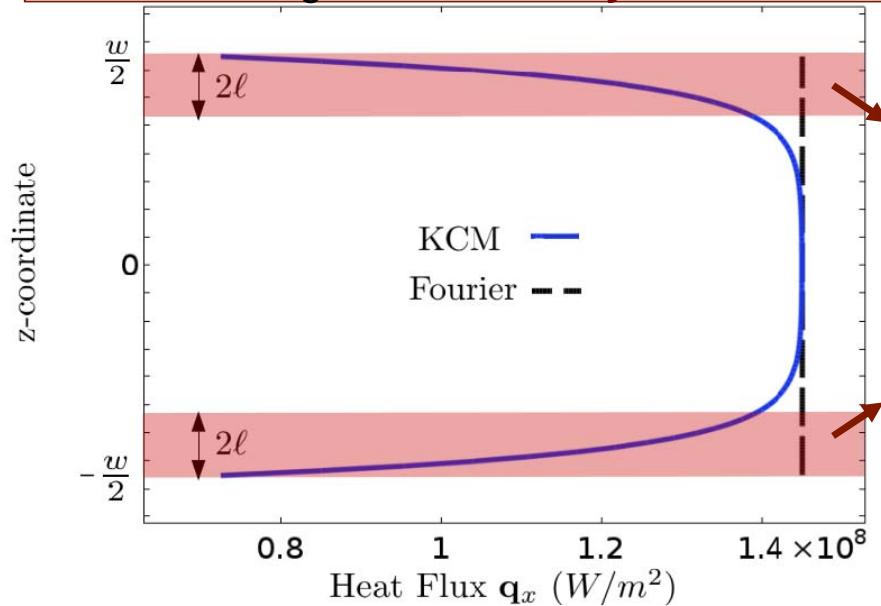
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12>> Experimental validation.

Silicon Thin Films

$$\kappa_{ef} = \frac{\int_{\Gamma} |\mathbf{q}| d\Gamma}{S \nabla T}$$

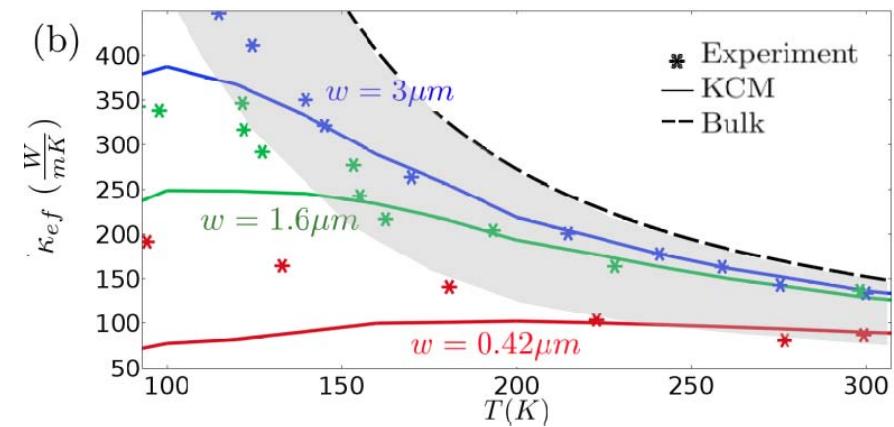
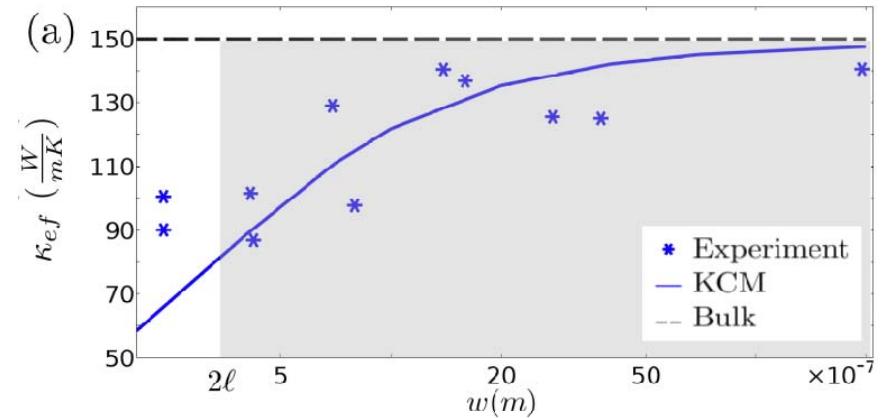
The effective thermal conductivity is lower than the Fourier prediction due to an effect analogous to **viscosity** in fluids.



Boundary conditions produce a non local reduction of the heat flux

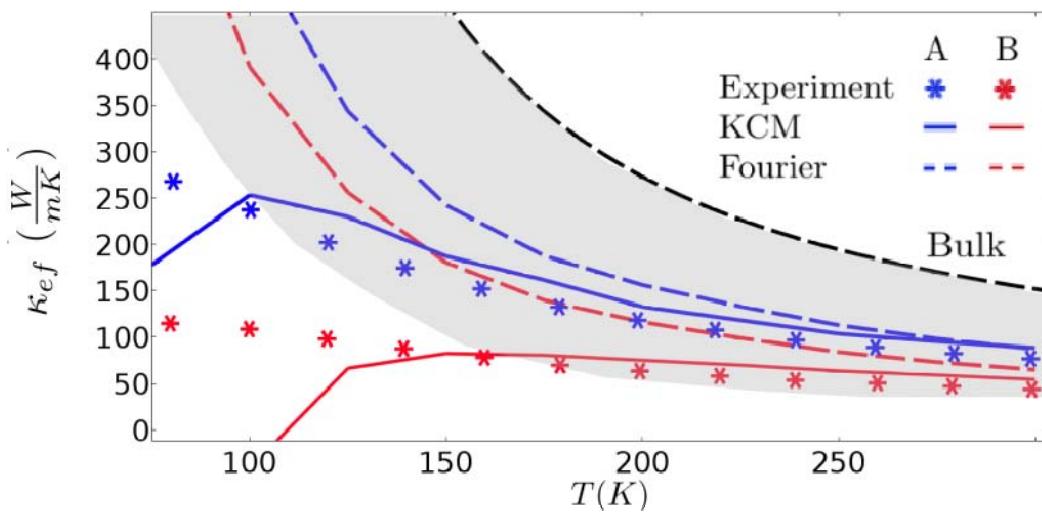
Region of applicability is indicated in gray.

$$2\ell < w$$



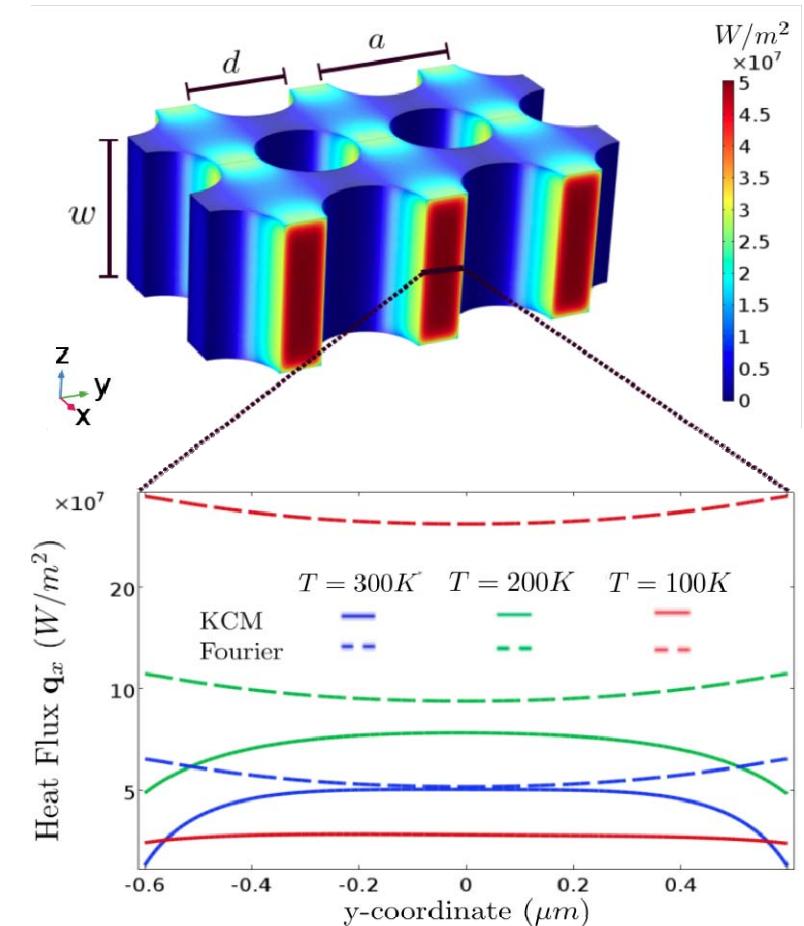
13>> Experimental validation.

Silicon Phononic Crystals

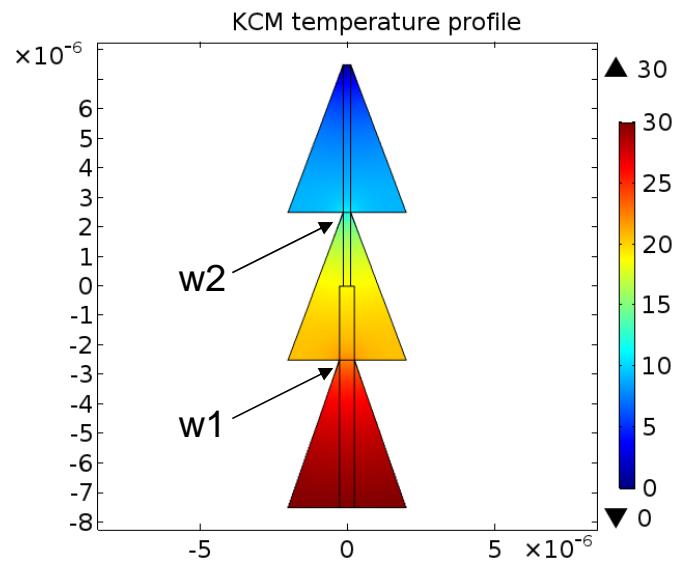


Phonic crystal A: $a = 4\mu m, d = 2.8\mu m, w = 4.49\mu m$

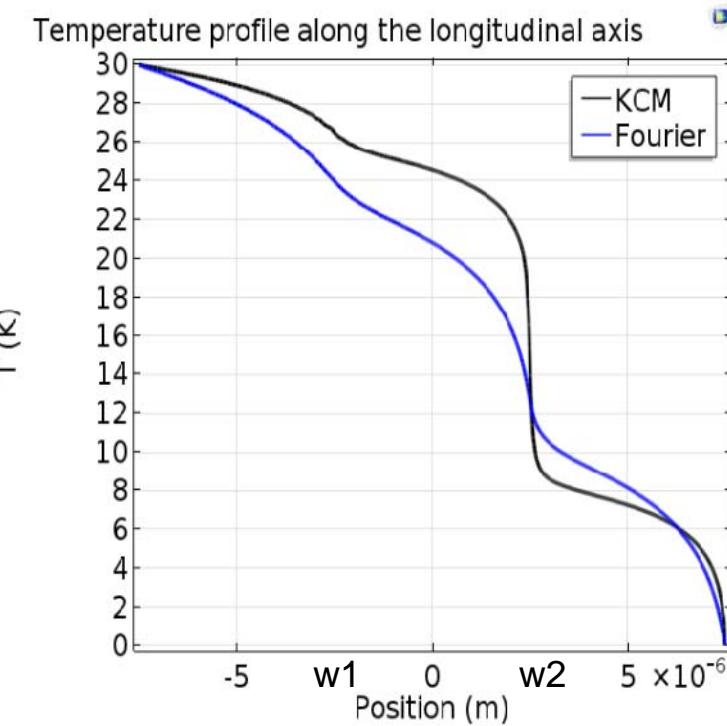
Phononic crystal B: $a = 20\mu m, d = 11.4\mu m, w = 4.84\mu m$



Suspended Silicon Structures



Low thermal conductivity is predicted in the narrower constriction.



Experimental validation in progress by the Eindhoven University of Technology.

- Fourier law breaks down when describing thermal transport at reduced length and time scales.
- Phonon hydrodynamics is a generalization of Fourier law obtained from the microscopic description of the phonon population.
- Phonon vorticity and viscosity appear as phenomenological explanations for the thermal behavior of nano scale devices.
- Numerical implementation of the equations in a COMSOL interface allows to predict heat transport in nanoscale complex geometries.

Acknowledgements

We acknowledge the support and advice of Mats Nigam (Sweden COMSOL office) and Nicolas Huc (France COMSOL office) during the development of the Nanoscale Heat Transfer COMSOL interface.

Thanks for your attention.